



DDR2 SO DIMM

TE Internal #: 1827236-4

SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .18 in [4.6 mm], Right Angle Module Orientation, Surface Mount Mount, DDR2 SO DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 2**

Stack Height: **4.6 mm [.18 in]**

Module Orientation: **Right Angle**

PCB Mounting Style: **Surface Mount**

Connector System: **Cable-to-Board**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

| | |
|-----------------------------------|--------------------------|
| DRAM Type | Double Data Rate (DDR) 2 |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |

Configuration Features

| | |
|---------------------|-------------|
| Number of Bays | 2 |
| Center Key | None |
| Number of Keys | 1 |
| Module Orientation | Right Angle |
| Number of Positions | 200 |
| Number of Rows | 2 |
| Keying | Standard |



Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.8 V |
|--------------|-------|

Signal Characteristics

| | |
|---------------|-------|
| SGRAM Voltage | 1.8 V |
|---------------|-------|

Body Features

| | |
|------------------------|-----------------|
| Ejector Location | Both Ends |
| Latch Material | Stainless Steel |
| Latch Plating Material | Tin |
| Module Key Type | SGRAM |
| Ejector Type | Locking |
| Connector Profile | Low |

Contact Features

| | |
|---|--------------|
| Socket Style | SO DIMM |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Current Rating (Max) | .5 A |
| Socket Type | Memory Card |

Termination Features

| | |
|-----------------|--------|
| Insertion Style | Cam-In |
|-----------------|--------|

Mechanical Attachment

| | |
|--------------------------|---------------|
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|--------------------------------|
| Centerline (Pitch) | .6 mm [.024 in] |
| Housing Material | High Temperature Thermoplastic |

Dimensions

| | |
|--------------|-----------------|
| Stack Height | 4.6 mm [.18 in] |
|--------------|-----------------|



Row-to-Row Spacing 5.6 mm[.22 in]

Usage Conditions

Operating Temperature Range -55 – 85 °C[-67 – 185 °F]

Operation/Application

Circuit Application Power

Industry Standards

UL Flammability Rating UL 94V-0

Packaging Features

Packaging Method Box, Tray

Packaging Quantity 20

Other

Comment Latch direct soldering type., See drawing for additional product information.

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU Compliant

EU ELV Directive 2000/53/EC Compliant

China RoHS 2 Directive MIIT Order No 32, 2016 No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006
 Current ECHA Candidate List: JUNE 2022 (224)
 Candidate List Declared Against: JUL 2021 (219)
 SVHC > Threshold:
 Not Yet Reviewed

Halogen Content Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability Reflow solder capable to 260°C

Product Compliance Disclaimer

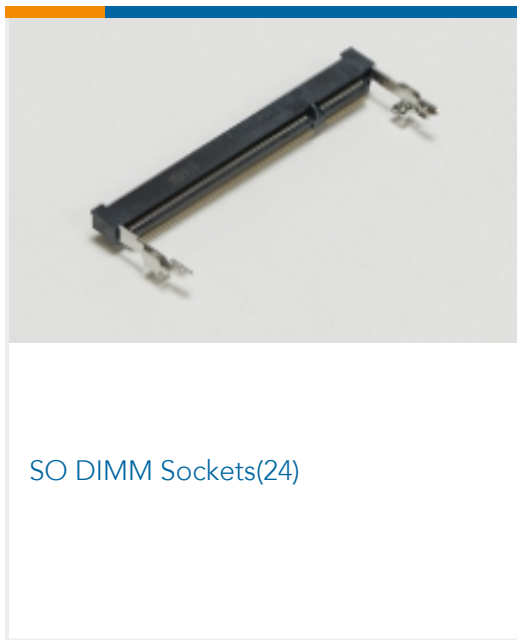
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

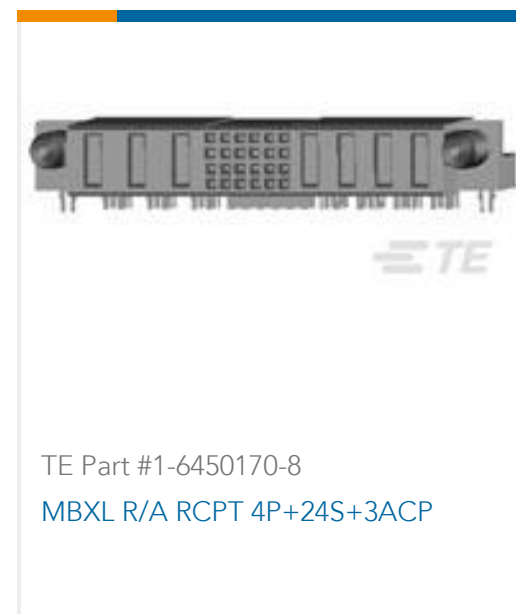
Compatible Parts



Also in the Series | DDR2 SO DIMM



Customers Also Bought





Documents

Product Drawings

[SEMI-HARD TRAY DDR2 SODIMM SOCKET 200P 4](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1827236-4_R1.2d_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1827236-4_R1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1827236-4_R1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Product Specification](#)

English

Product Environmental Compliance

[TE Material Declaration](#)

English